



SLOVENSKI STANDARD

oSIST prEN 62680-1-2:2020

01-september-2020

**Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2.
del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB**

Universal serial bus interfaces for data and power - Part 1-2: Common components -
USB Power Delivery specification

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ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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en,fr,de

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100/3440/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

PROJECT NUMBER: IEC 62680-1-2 ED5	
DATE OF CIRCULATION: 2020-07-03	CLOSING DATE FOR VOTING: 2020-09-25
SUPERSEDES DOCUMENTS: 100/3403/RR	

IEC TA 18 : MULTIMEDIA HOME SYSTEMS AND APPLICATIONS FOR END-USER NETWORKS	
SECRETARIAT: Japan	SECRETARY: Mr Keisuke Koide
OF INTEREST TO THE FOLLOWING COMMITTEES:	PROPOSED HORIZONTAL STANDARD: <input type="checkbox"/> Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: <input type="checkbox"/> EMC <input type="checkbox"/> ENVIRONMENT <input type="checkbox"/> QUALITY ASSURANCE <input type="checkbox"/> SAFETY	
<input checked="" type="checkbox"/> SUBMITTED FOR CENELEC PARALLEL VOTING	<input type="checkbox"/> NOT SUBMITTED FOR CENELEC PARALLEL VOTING
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TITLE:

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

PROPOSED STABILITY DATE: 2025

NOTE FROM TC/SC OFFICERS:

INTERNATIONAL ELECTROTECHNICAL COMMISSION

UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 1-2: Common components – USB Power Delivery specification

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or
- amended.

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This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision 3.0, Version 2.0.

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Universal Serial Bus Power Delivery Specification

Revision: 3.0

Version: 2.0

Release date: 29 August 2019

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Joshua Warner	Qualcomm, Inc	Wanfeng Zhang	Silergy Corp.
Karyn Vuong	Qualcomm, Inc	Kafai Leung	Silicon Laboratories, Inc.
Lalan Mishra	Qualcomm, Inc	Kok Hong Soh	Silicon Laboratories, Inc.
Vamsi Samavedam	Qualcomm, Inc	Sorin Badiu	Silicon Laboratories, Inc.
Vatsal Patel	Qualcomm, Inc	Steven Ghang	Silicon Laboratories, Inc.
Chris Sporck	Qualcomm, Inc.	Abhishek Sardeshpande	SiliConch Systems Private Limited
Craig Aiken	Qualcomm, Inc.	Aniket Mathad	SiliConch Systems Private Limited
Narendra Mehta	Qualcomm, Inc.	Chandana N	SiliConch Systems Private Limited
Terry Remple	Qualcomm, Inc.	Jaswanth Ammineni	SiliConch Systems Private Limited
Will Kun	Qualcomm, Inc.	Jinisha Patel	SiliConch Systems Private Limited
Yoram Rimoni	Qualcomm, Inc.	Kaustubh Kumar	SiliConch Systems Private Limited
Fan-Hau Hsu	Realtek Semiconductor Corp.	Nitish Nitish	SiliConch Systems Private Limited
Tsung-Peng Chuang	Realtek Semiconductor Corp.	Pavitra Balasubramanian	SiliConch Systems Private Limited

Rakesh Polasa	SiliConch Systems Private Limited	Tony Minchell	Teledyne-LeCroy
Satish Anand Verkila	SiliConch Systems Private Limited	Anand Dabak	Texas Instruments
Shubham Paliwal	SiliConch Systems Private Limited	Bill Waters	Texas Instruments
Vishnu Pusuluri	SiliConch Systems Private Limited	Bing Lu	Texas Instruments
John Sisto	SMSC	Deric Waters	Texas Instruments
Ken Gay	SMSC	Grant Ley	Texas Instruments
Mark Bohm	SMSC	Gregory Watkins	Texas Instruments
Richard Wahler	SMSC	Ingolf Frank	Texas Instruments
Shannon Cash	SMSC	Ivo Huber	Texas Instruments
Tim Knowlton	SMSC	Javed Ahmad	Texas Instruments
William Chiechi	SMSC	Jean Picard	Texas Instruments
Shigenori Tagami	Sony Corporation	John Perry	Texas Instruments
Shinichi Hirata	Sony Corporation	Martin Patoka	Texas Instruments
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Bob Dunstan	Specwerkz	Scott Jackson	Texas Instruments
Diane Lenox	Specwerkz	Shafiuddin Mohammed	Texas Instruments
Michael Munn	StarTech.com Ltd.	Srinath Hosur	Texas Instruments
Fabien Friess	ST-Ericsson	Steven Tom	Texas Instruments
Giuseppe Platania	ST-Ericsson	Yoon Lee	Texas Instruments
Jean-Francois Gatto	ST-Ericsson	Tim Wilhelm	The Silanna Group Pty. Ltd.
Milan Stamenkovic	ST-Ericsson	Tod Wolf	The Silanna Group Pty. Ltd.
Nicolas Florenchie	ST-Ericsson	Chris Yokum	Total Phase
Patrizia Milazzo	ST-Ericsson	Brad Cox	Ventev Mobile
Christophe Cochard	STMicroelectronics	Colin Vose	Ventev Mobile
Christophe Lorin	STMicroelectronics	Dydron Lin	VIA Technologies, Inc.
Filippo Bonaccorso	STMicroelectronics	Fong Jim Wang	VIA Technologies, Inc.
Jessy Guilbot	STMicroelectronics	Jay Tseng	VIA Technologies, Inc.
Joel Huloux	STMicroelectronics	Rex Chang	VIA Technologies, Inc.
John Bloomfield	STMicroelectronics	Terrance Shih	VIA Technologies, Inc.
Massimo Panzica	STMicroelectronics	Ho Wen Tsai	Weltrend Semiconductor
Meriem Mersel	STMicroelectronics	Hung Chiang	Weltrend Semiconductor
Nathalie Ballot	STMicroelectronics	Jeng Cheng Liu	Weltrend Semiconductor
Pascal Legrand	STMicroelectronics	Priscilla Lee	Weltrend Semiconductor
Patrizia Milazzo	STMicroelectronics	Wayne Lo	Weltrend Semiconductor
Richard O'Connor	STMicroelectronics	Charles Neumann	Western Digital Technologies, Inc.
Morten Christiansen	Synopsys, Inc.	Curtis Stevens	Western Digital Technologies, Inc.
Nivin George	Synopsys, Inc.	John Maroney	Western Digital Technologies, Inc.
Zongyao Wen	Synopsys, Inc.	Joe O'Brien	Wilder Technologies
Joan Marrinan	Tektronix	Will Miller	Wilder Technologies
Kimberley McKay	Teledyne-LeCroy	Juejia Zhou	Xiaomi Communications Co., Ltd.
Matthew Dunn	Teledyne-LeCroy	Xiaoxing Yang	Xiaomi Communications Co., Ltd.